ABSTRACT

MULTI-LEADFRAME SEMICONDUCTOR PACKAGE AND METHOD OF MANUFACTURE

A multi-leadframe semiconductor package and method of manufacture includes a first leadframe having a die pad and a plurality of contact leads around the periphery of the die pad. A die is attached to the die pad and electrically connected to the plurality of contact leads. A heat spreader leadframe having a heat spreader and a plurality of terminal leads around the periphery of the heat spreader is provided. The die pad is attached to the heat spreader, and the plurality of contact leads is attached to the plurality of terminal leads. (Fig. 2)